50.046 Cloud Computing and IoT

Embedded devices

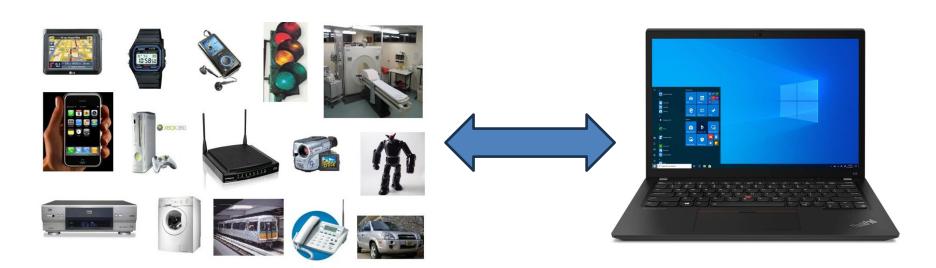
2023 Term 7

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Definition

- What is an embedded system?
 - Purposely-built system (hardware / software) serving some
 specific / dedicated application
 - Implications:
 - Minimize cost / size / energy consumption
 - Resource constrained



Outline

- Processor types
 - MCU vs MPU
- Computer architecture
 - Based on instruction set and memory
- ESP32 as an example
 - Processor
 - Memory
 - I/O peripheral

Processor Types

MCU vs. MPU

What is a Microcontroller (MCU)?

- Single chip
- Processor + Memory + I/O
- Application-specific
- Low-power consumption

- Examples
 - Digital thermometer
 - Automatic coffee maker
 - Washing machine

What is a Microprocessor (MPU)?

- General-purpose
- Requires external components
- Higher computational power
- Versatile but power-consuming
- Examples
 - Laptops
 - Servers
 - High-end drones

Key Differences - Memory

- MCU: Onboard RAM and flash
- MPU: External memory

- Example:
 - MCU: Arduino, ESP32
 - MPU: Raspberry Pi, Smartphone chips

Key Differences - Power Consumption

- MCU: Low-power, battery-operable
- MPU: Higher power consumption

- Example
 - MCU: Fitness trackers
 - MPU: Gaming consoles

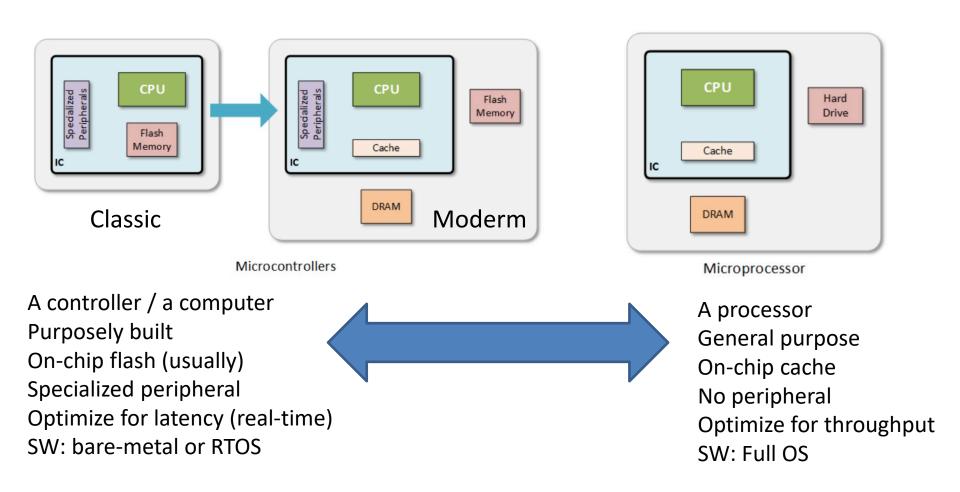
Key Differences - I/O Capabilities

- MCU: Built-in I/O capabilities
- MPU: Requires external I/O controllers

Example:

- MCU: ESP32 with WiFi
- MPU: Desktop PC with external network card

Evolution of MCU



Computer Architecture

von Neumann vs. Harvard RISC vs. CISC

Computer architecture in a nutshell

- Separation of **Processor** and **memory** distinguishes programmable computer
- Processor fetches instructions from memory
- Registers help out: program counter (PC), instruction register (IR), general-purpose registers, etc.

Computer architecture categories

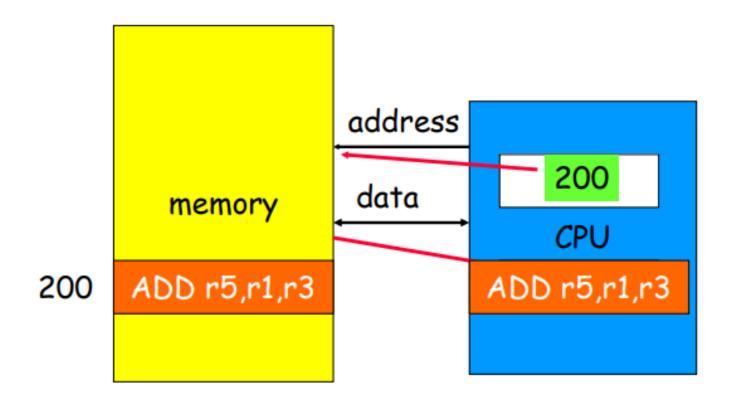
- If instruction and data share memory and buses
 - von Neumann vs. Harvard

Bus is a communication system that transfers data between components inside a computer

- Data buses
- Address buses

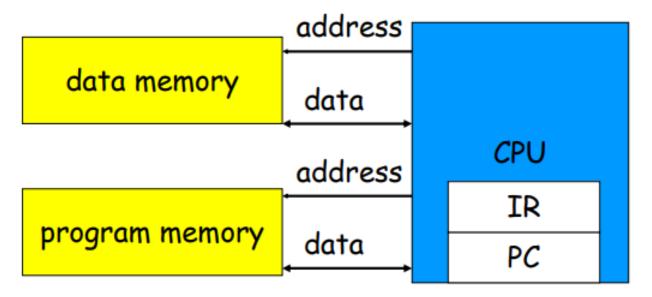
von Neumann architecture

- Same memory holds data, instructions.
- A single set of address/data buses between processor and memory



Harvard architecture

- Named after Harvard Mark I, an IBM computer in WWII
- Separate memories for data and instructions.
- Two sets of address/data buses between processor and memory
 - Greater memory bandwidth

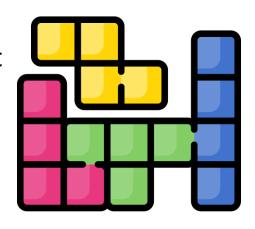


Computer architecture categories

- If instruction and data share memory and buses
 - von Neumann vs. Harvard
- Based on processor instruction sets architecture (ISA)
 - RISC vs. CISC

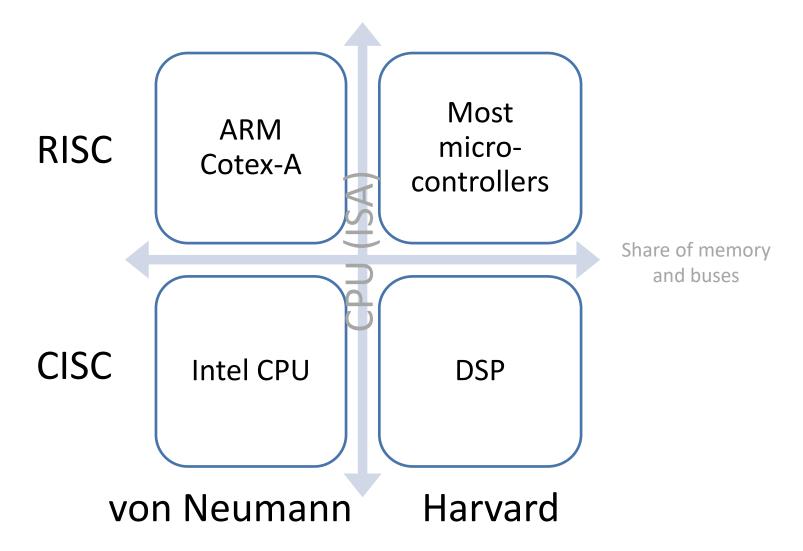
RISC vs CISC

- Reduced Instruction Set Computer (RISC)
 - Compact, uniform instructions -> facilitate pipelining
 - More lines of code -> large memory footprint
 - Allow effective compiler optimization
- Complex Instruction Set Computer (CISC)
 - Many addressing modes and long instructions
 - High code density
 - Often require manual optimization of assembly code for embedded systems



Like Tetris!

Microprocessors

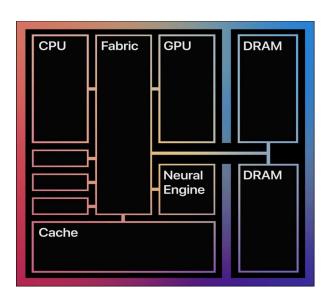


Case Study: Apple's M1 chip

- ISA is ARMv8.5-A
- The high-performance cores have an unusually large 192 KB of L1 instruction cache and 128 KB of L1 data cache and share a 12 MB L2 cache
- The M1 uses a 128-bit LPDDR4X SDRAM in a unified memory configuration shared by all the components of the processor.
- Integrated memory, GPU, NPUs, decoders, ...

Question:

What architectural designs are adopted?



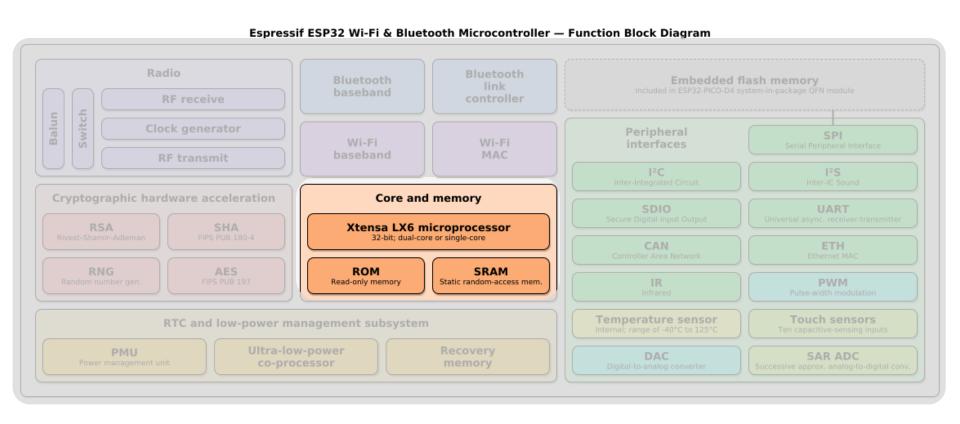
How about ESP32?

ESP32 MCU function block diagram

Espressif ESP32 Wi-Fi & Bluetooth Microcontroller — Function Block Diagram Radio **Bluetooth** Bluetooth **Embedded flash memory** link baseband Included in ESP32-PICO-D4 system-in-package QFN module controller RF receive Switch Balun Clock generator Peripheral SPI Wi-Fi Wi-Fi interfaces Serial Peripheral Interface baseband MAC RF transmit I2C I2S Inter-Integrated Circuit Inter-IC Sound Cryptographic hardware acceleration Core and memory **SDIO** UART Secure Digital Input Output Universal async. receiver-transmitter RSA SHA Xtensa LX6 microprocessor FIPS PUB 180-4 32-bit; dual-core or single-core Rivest-Shamir-Adleman CAN ETH Controller Area Network Ethernet MAC RNG AES ROM SRAM Random number gen. FIPS PUB 197 Read-only memory Static random-access mem. IR **PWM** Infrared Pulse-width modulation Temperature sensor Touch sensors RTC and low-power management subsystem Internal; range of -40°C to 125°C Ten capacitive-sensing inputs Ultra-low-power Recovery PMU DAC SAR ADC Power management unit co-processor memory Digital-to-analog converter Successive approx. analog-to-digital conv.

22

ESP32 MCU function block diagram

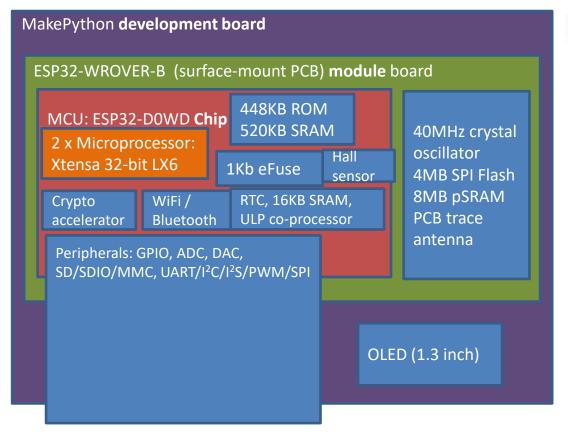


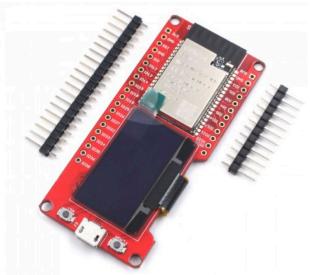
ESP32 processor

- Xtensa 32-bit LX6
 - IP core from Tensilica (part of Cadence design system)
 - RISC Instruction Set Architecture (ISA)
 - Harvard architecture
 - 4 GB (32-bit) address space for both data bus and instruction bus
 - 240 MHz
- Two LX6 cores in ESP32
 - Protocol core + application core

Integration levels

System-on-a-Chip (SoC) vs. System-on-Module (SoM)
 vs. development board

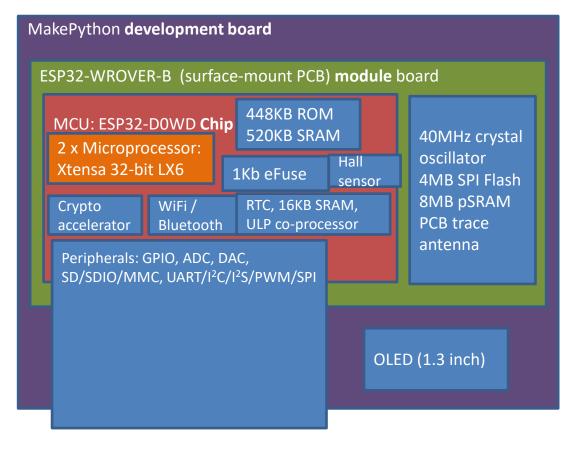




MakePython ESP32
Development Board

Integration levels

System-on-a-Chip (SoC) vs. System-on-Module (SoM)
 vs. development board



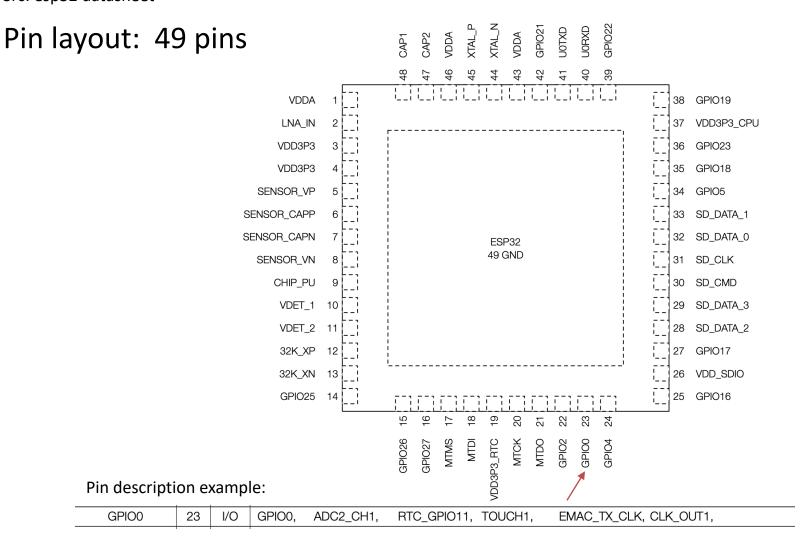
Level 0: Xtensa 32-bit LX microprocessors (IP core from Cadence Tensilica)

Level 1: ESP32-D0WD chip (by Espressif, TSMC 40nm technology, 5mm x 5mm, ~1 USD)

Level 2: WROVER-B module (by Espressif, 31.4mm x 18mm, ~5 USD)

Level 3: MakePython ESP32 development board (by Makerfabs, 70mm x 32.6mm, , ~15 USD)

ESP32 SoC pin definition Src: esp32 datasheet



Pins can be reused

ESP32-WROVER module pin definition Src: esp32-wrover datasheet

Pin layout: 39 pins

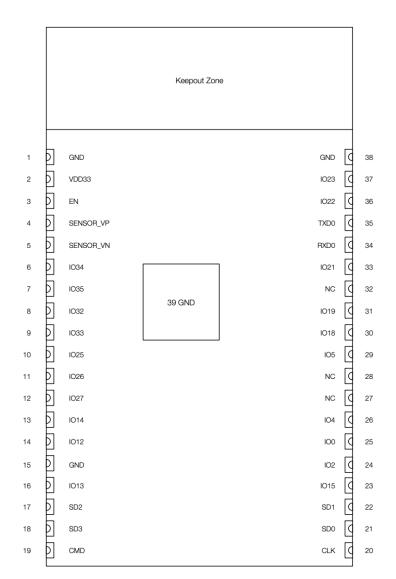


Figure 1: Pin Layout of ESP32-WROVER (Top View)

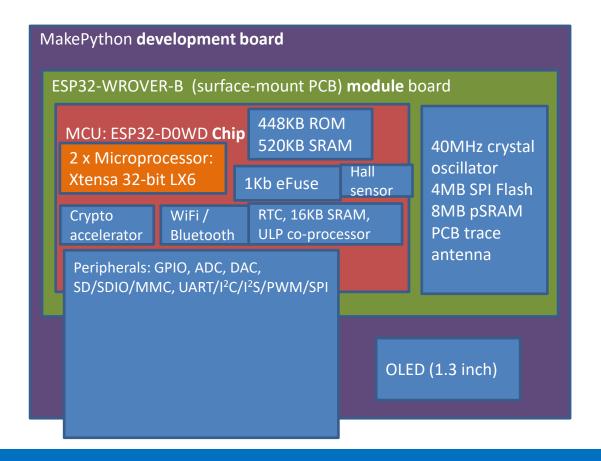
Makepython Pinout

Pin layout: 32 pins 3V3 5V0 GND O GND C GND GND Wakerfabs RST EOI (103 **RST RXD** 函 GND O GND 101 **TXD** AD2CH2 102 AD2CH1 102 001 100 TCH1 AD2CH0 **HMOSO** AD2CH5 1012 104 **SDA** IO12 vcs AD2CH4 1013 105 (O) 1013 **SCL HMOSI** AD2CH6 1014 O 1014 HSCK 1015 O 1015 HCS AD2CH3 VSCK 1018 O 1018 LZOI 🔘 1021 OIOSS VMISO 1019 IO19 1022 DAC1 AD2CH8 1025 0 1025 IO23 VMOSI 1023 AD2CH9 1026 O 1026 DAC₂ 1027 (O) 1027 TCH7 AD2CH7 MakePython ESP32 O 1032 1032 TCH9 AD1CH4 (O) IO33 1033 TCH8 AD1CH5 1034 **O** 1034 AD1CH6 IO35 1035 AD1CH7 IO36 1036 AD1CH0 O 1039 1039 AD1CH3 SEATH OF SEATH

MCU: Evolution

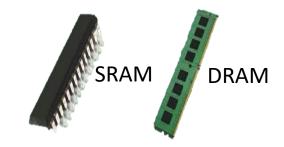
Buses	Example MCU Chip	Example boards	Spec
4 bit	TMS 1000 (Texas Instruments)	Dated 1974	1KB ROM, 256b RAM
8 bit	AVR ATmega328P (Microchip)	Arduino Uno Rev3	20MHz 32 KB Flash, 2KB SRAM
16 bit	MSP430G2553 (Texas Instruments)	TI MSP- EXP430G2ET kit	16MHz 16KB Flash, 512B SRAM
32 bit	Kinetis KL26Z (NXP): ARM® Cortex-M0+, ARMv6-M	Micro:Bit	48MHz 128KB Flash, 16KB SRAM
	STM32F103C8T6 (STMicroelectronics): ARM® Cortex- M3 core, ARMv7-M	STM32duino (blue pill)	72MHz 128KB Flash, 20KB SRAM
	ESP32-D0WD (Espressif): Xtensa LX6	ESP32 development board	240MHz, 448KB ROM Off-chip Flash, 520KB SRAM

How about the memories/storage?



What's the difference between cache, main memory, and flash?

Memory: Types



- Random access memory (RAM)
 - Static RAM (SRAM): cache memory in CPUs, certain high-speed registers.
 - Dynamic RAM (DRAM): main memory in computers, smartphones, tablets, etc.
 - **Pseudostatic RAM (PSRAM)**: IoT, mobile devices, MP3, game consoles.
 - Non-volatile RAM (NVRAM)
 - Ferroelectric RAM (FeRAM): smart card and RFID.

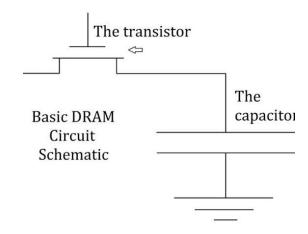
SRAM vs DRAM

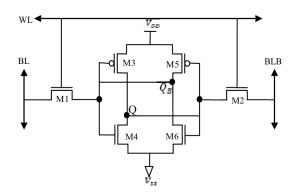
Basic Operation:

- DRAM: periodic refreshing the memory to maintain the data it holds, where "dynamic" comes from.
- SRAM: no reflesh cycle. Hold data as long as power applies.

Structure:

- DRAM: uses a single transistor and a capacitor to store each bit of data. Over time, the charge in the capacitor leaks, which necessitates the refresh cycles.
 - PSRAM is DRAM with in-built reflash circuit. Perform like SRAM.
- SRAM: uses six transistors to store each bit of data, which makes it faster but also more expensive in terms of silicon area.





SRAM Schematic Diagram

SRAM vs DRAM

- Speed
 - DRAM: Generally slower than SRAM because of the refresh cycles required.
 - SRAM: Faster access times than DRAM.
- Power consumption
 - DRAM: More power during active use because of the refresh cycles, but has lower leakage (standby) power due to the capacitive storage.
 - SRAM: Generally consumes more power in standby mode since it requires power to hold data, but it can consume less power during active use as there are no refresh cycles.
- Density: DRAM higher than SRAM

Memory: Types

- Read-only memory (ROM)
 - Traditionally considered non-volative and "readonly"
 - Programmable read-only memory (PROM)
 - EEPROM (also E²PROM): electrically erasable programmable read-only memory (byte-level erase block)
 - Flash memory (high speed / density, but larger erase block)

Memory Type	Volatility	Speed	Cost	Typical Use	Retains Data When Power Off?
DRAM	Volatile	Fast	Low	General- purpose storage	No
SRAM	Volatile	Very Fast	High	High-speed cache	No
PSRAM	Volatile	Moderate	Moderate	Expanded storage	No
NVRAM	Non-Volatile	Slow	Moderate	Settings, states	Yes
ROM	Non-Volatile	Slow	Low	Firmware	Yes
EEPROM	Non-Volatile	Moderate	Moderate	Config data, (erasable)	Yes

ESP32 chip Memory

Embedded Memory

- 448 KB Internal ROM (ROM0 384K + ROM1 64K)
- 520 KB Internal SRAM (RAMO 192K + RAM1 128K + RAM2 200K)
- 8 KB RTC FAST Memory (SRAM)
- 8 KB RTC SLOW Memory (SRAM)
- No on-chip Flash memory

External Memory (through QSPI)

- Supports up to 16 MB off-Chip Flash
- Supports up to 8 MB off-Chip SRAM

Speed difference between on & off chip memory: an example

• ESP32:

- Internal SRAM (520KB) is 32bit @ 240MHz max, so960MByte/second
- Quad SPI connected PSRAM and Flash memory (they share the same QSPI) is 4-bit @ 80MHz, so
 40MByte/second

Question:

How to address speed difference?

ESP32 memory

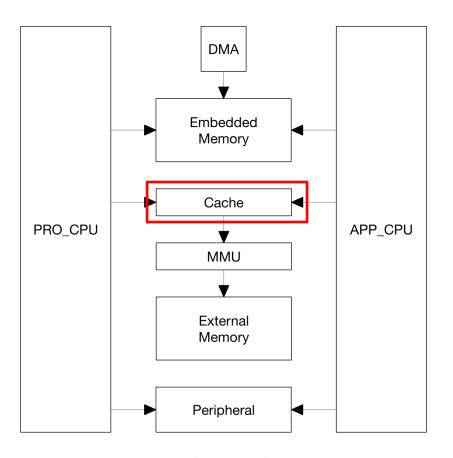


Figure 1: System Structure

Source: ESP32 Technical Reference Manual

Memory Address Mapping

Table 4: Embedded Memory Address Mapping

Puo Typo	Boundary	/ Address	Ciro	Torqut	Comment		
Bus Type	Low Address	High Address	Size	Target	Comment		
Data	0x3FF8_0000	0x3FF8_1FFF	8 KB	RTC FAST Memory	PRO_CPU Only		
	0x3FF8_2000	0x3FF8_FFFF	56 KB	Reserved	-		
Data	0x3FF9_0000	0x3FF9_FFFF	64 KB	Internal ROM 1	-		
	0x3FFA_0000	0x3FFA_DFFF	56 KB	Reserved	-		
Data	0x3FFA_E000	0x3FFD_FFFF	200 KB	Internal SRAM 2	DMA		
Data	0x3FFE_0000	0x3FFF_FFFF	128 KB	Internal SRAM 1	DMA		
Rus Typo	Boundary	/ Address	Size	Target	Comment		
Bus Type	Low Address	High Address	Size	Target	Comment		
Instruction	0x4000_0000	0x4000_7FFF	32 KB	Internal ROM 0	Remap		
Instruction	0x4000_8000	0x4005_FFFF	352 KB	Internal ROM 0	-		
	0x4006_0000	0x4006_FFFF	64 KB	Reserved	-		
Instruction	0x4007_0000	0x4007_FFFF	64 KB	Internal SRAM 0	Cache		
Instruction	0x4008_0000	0x4009_FFFF	128 KB	Internal SRAM 0	-		
Instruction	0x400A_0000	0x400A_FFFF	64 KB	Internal SRAM 1	-		
Instruction	0x400B_0000	0x400B_7FFF	32 KB	Internal SRAM 1	Remap		
Instruction	0x400B_8000	0x400B_FFFF	32 KB	Internal SRAM 1	-		
Instruction	0x400C_0000	0x400C_1FFF	8 KB	RTC FAST Memory	PRO_CPU Only		
Bus Type	Boundary	/ Address	Size	Torgot	Comment		
	Low Address	High Address	Size	Target	Comment		
Data Instruc-	0x5000_0000	0x5000_1FFF	8 KB	RTC SLOW Memory	_		
tion 0x3000_0000		0.0000_1111	O ND	TITO GLOVV IVIGITIOTY			

Source: ESP32 Technical Reference Manual V4.3

Another view (including peripheral)

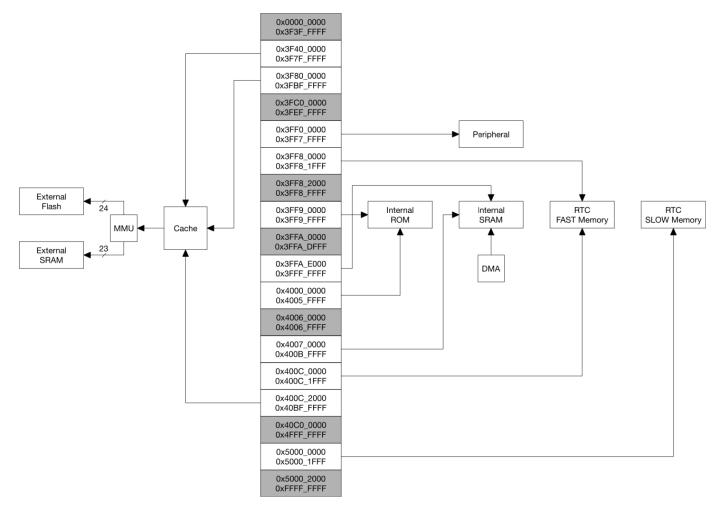


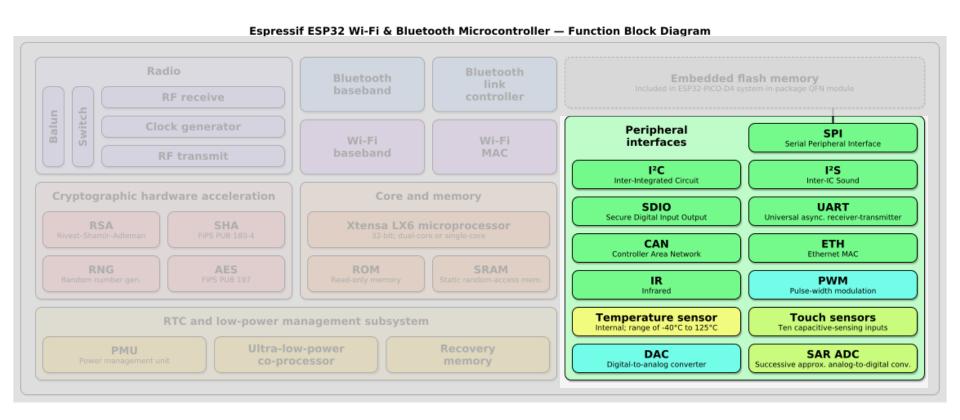
Figure 2: System Address Mapping

Source: ESP32 Technical Reference Manual

I/O Peripheral

Overview

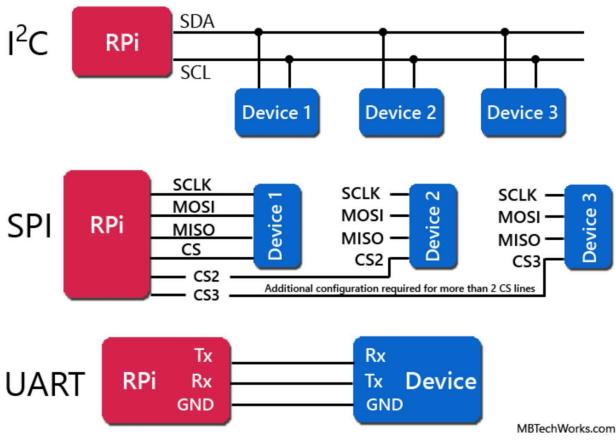
ESP32 MCU function block diagram



I/O Peripherals

- UART (Universal Asynchronous Receiver-Transmitter)
 - 3x in ESP32
- I²C (inter-integrated circuit)
 - 2x in ESP32
- SPI (Serial Peripheral Interface)
 - 4x in ESP32

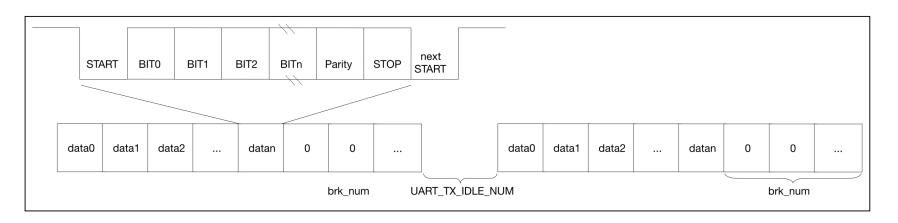
Comparison (src: MBTechWorks.com)



I2C, SPI, UART Connection Diagram

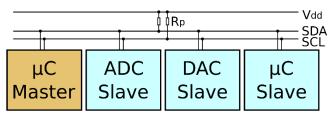
UART

- Universal Asynchronous Receiver-Transmitter
 - character-oriented data link
 - Asynchronous --- no clock wire needed
 - Need to agree on baud rate (e.g., 115200bps) and other settings (data length, STOP bits, parity bits)



I²C (inter-integrated circuit)

- I²C: 100kbps, 400kbps, 5Mbps (ultra fast-mode)
 - History: Philips Semiconductor (now NXP), 1982
 - Synchronous, multi-master, multi-slave, packet switched, serial comm bus
 - Design objectives:
 - simplicity, low manufacturing cost
 - 2 wires:
 - SDA (Serial Data Line), SCL (Serial Clock Line)
 - ACK for successful transmission
 - Open-drain design, pull-up resisters needed
 - Applications: low-speed DAC/ADC, small OLED/LCD display, hardware configure / monitor / diagnostic, access RTC and NVRAM



I²C addressing

• 7-bit addressing

Field:	S	I ² C address field F							R/W'	Α	I ² C message sequences	Р
Туре		Byte 1										
Bit position in byte X		7	5 5	4	3	2	1	0		Byte X etc		
7-bit address pos	Start	7	6	5	4	3	2	1		ACK	Rest of the read or write	Stop
Note		MSB						LSB	1 = Read		message goes here	
Note		MSB						LOD	0 = Write			

• 10-bit addressing

Field:	S	10-l	bit m	ode	indica	ator	Upper a	addr	R/W'	Α	Lower address field								I ² C message sequences	Р
Туре						Ву	rte 1						В	yte	2					
Bit position in byte X		7	6	5	5 4	3	2	1	0		7	7 6	5	4	3	2	1	0	Byte X etc.	
Bit value	Start	1	1	1	1	0 X X X		Х	ACK	X	X	X	X	X	X	X	X	Rest of the read or write	Stop	
10-bit address pos	Start						10	9		ACK	8	7	6	5	4	3	2	1		Зюр
Niete		L. dia da a 40 hit a da					мор		1 = Read									1 OD	message goes here	
Note		Indicates 10-bit mode			MSB		0 = Write									LSB	51			

SPI (Serial Peripheral Interface)

- Synchronous serial communication
 - History: Motorola, 1980
 - Use: Flash memory, LCD



- Full duplex, master-slave (single master)
 - Dual SPI, Quad SPI (these are half-duplex)
- Four-wire serial bus: SCLK, MOSI, MISO, SS (Slave select)
 - No ACK for successful data transfer
- Clock polarity & phase (mode #)
- No top speed limit => 10Mbps or more

Slave

Quad SPI

Summary

- Inside an embedded system
 - Processor, memory, I/O
- MCU vs. MPU
 - MCU: integrated processor, memory, I/O
 - MPU: separated
- Inside the processor
 - Instruction set architecture (ISA): RISC vs. CISC
 - Instruction and data
 - Share memory and buses (von Neumann)
 - Separated memory and buses (Harvard)

Summary

- Memory
 - RAM vs ROM
 - RAM: SRAM vs. DRAM vs. PSRAM vs. NVRAM
 - ROM: traditionally considered "read-only" but now with EEPROM and Flash
- I/O peripheral
 - A glance at UART, I2C, SPI
 - More to go next Monday

Resources

- ESP32 Technical Reference Manual Espressif Systems
 https://www.espressif.com/sites/default/files/documentation/esp32_technic
 al reference manual en.pdf
- ESP-IDF (Espressif IoT Development Framework)
 https://docs.espressif.com/projects/esp-idf/en/latest/esp32/get-started/index.html
- ESP32 Microcontroller Hardware and Software https://www.youtube.com/watch?v=xU-Kxhd0jEw
- ESP32 Teardown
 https://www.youtube.com/watch?v=ZQXpfKDbXKs
- https://medium.com/the-esp-journal/esp32-memory-analysis-case-studyeacc75fe5431
- https://semiengineering.com/mpu-vs-mcu/